

FIG.1A

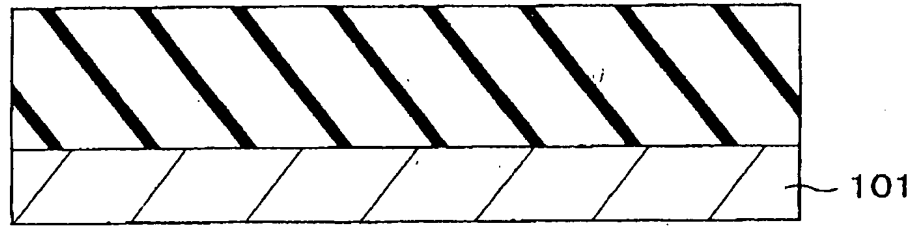


FIG.1B

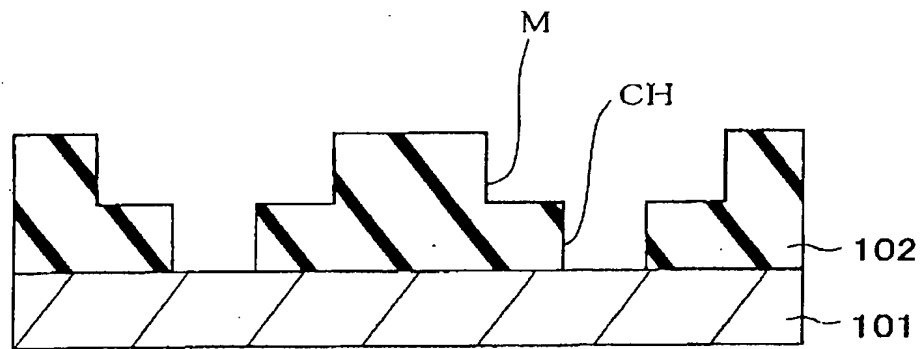


FIG.1C

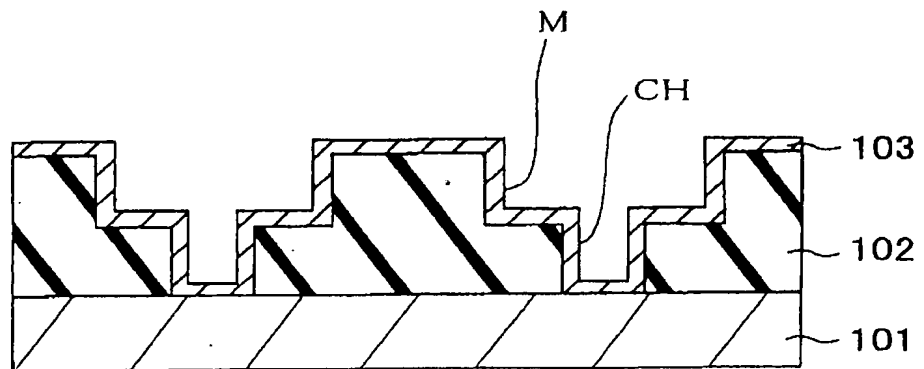


FIG.2A

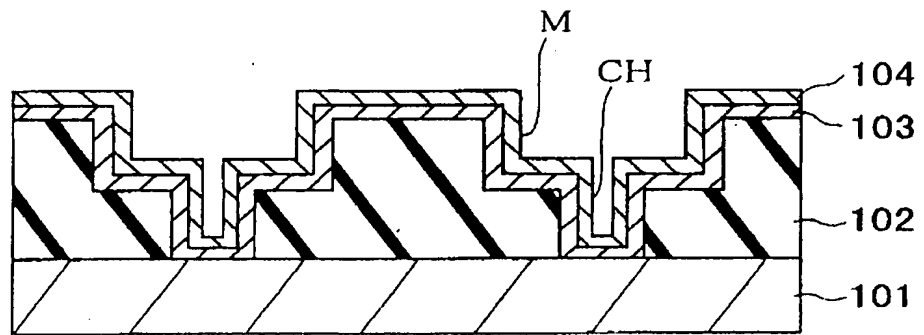


FIG.2B

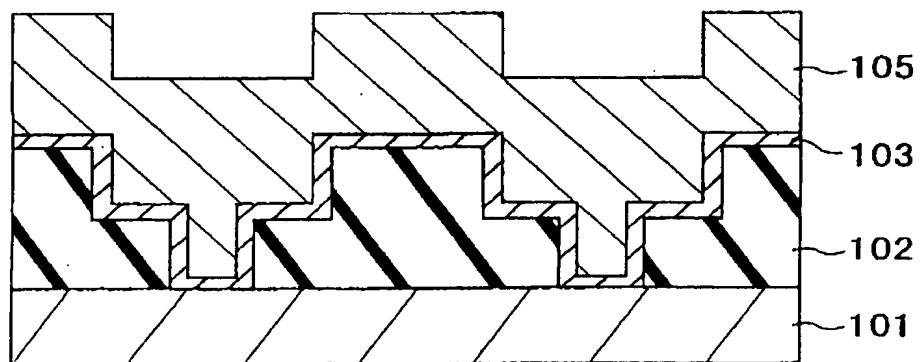


FIG.3A

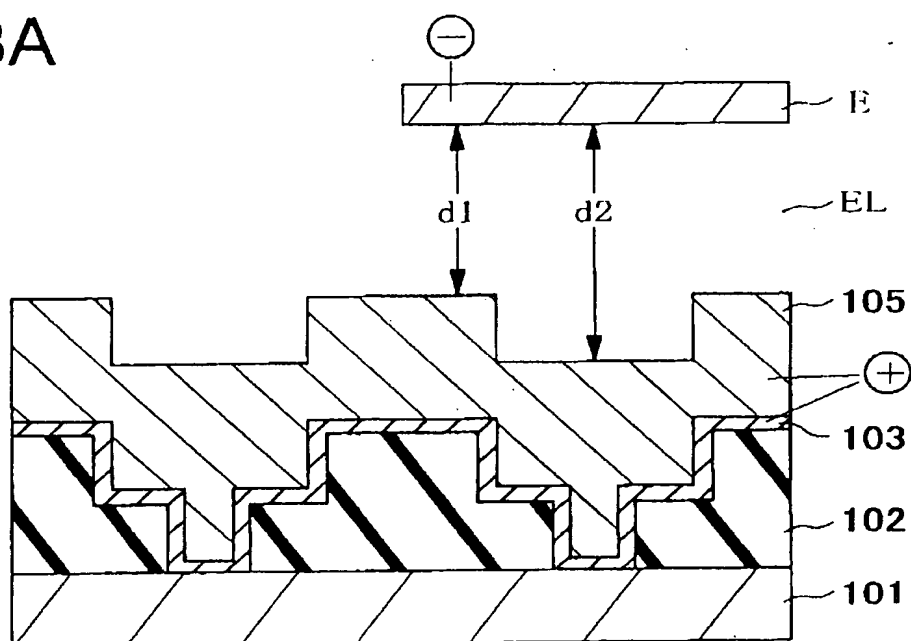


FIG.3B

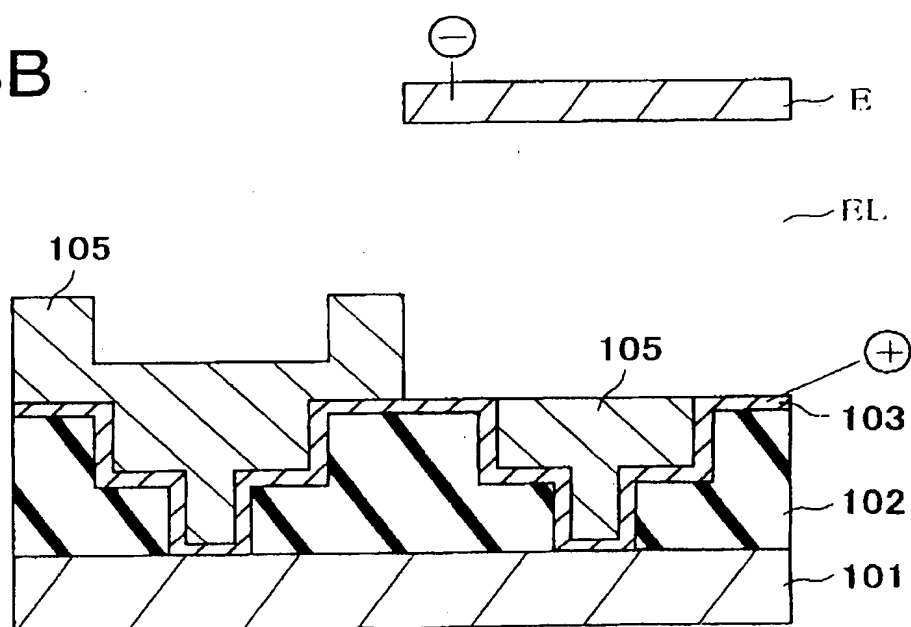


FIG.4A

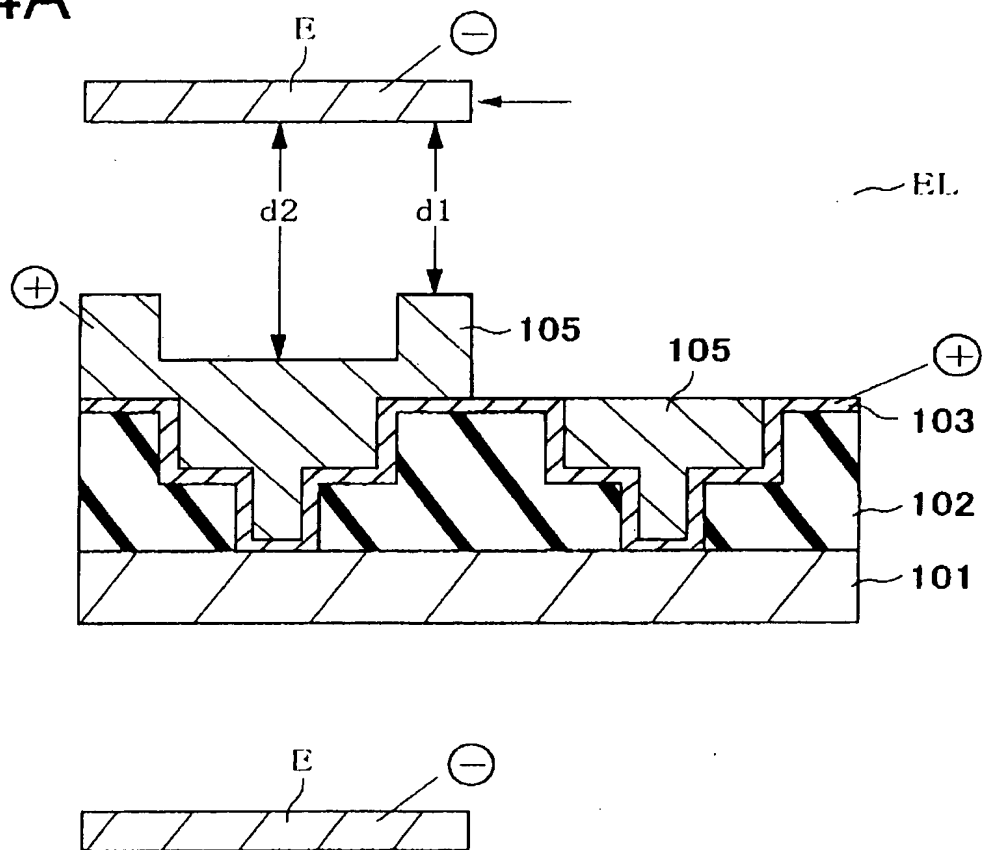


FIG.4B

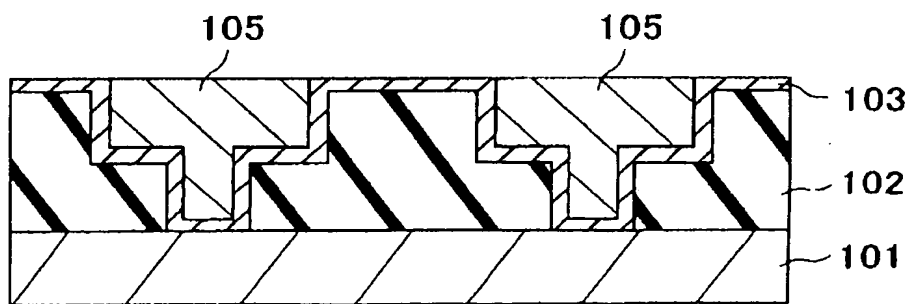


FIG. 5

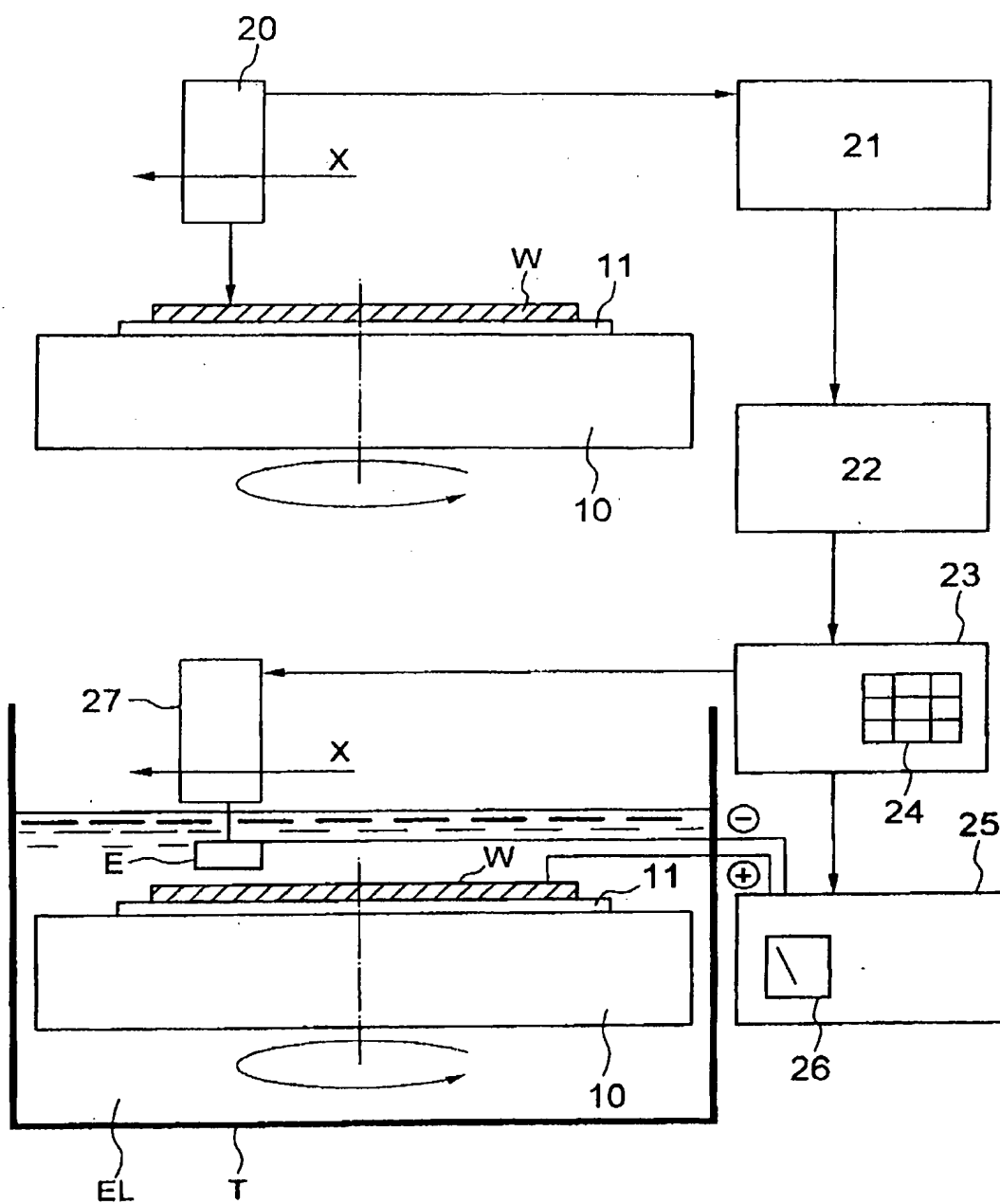


FIG. 5

FIG.6A

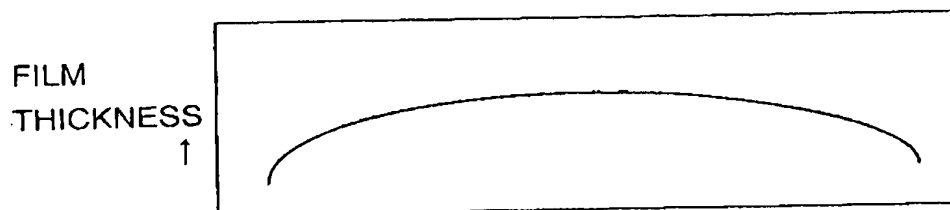


FIG.6B

AMOUNT OF
REMOVAL
↑

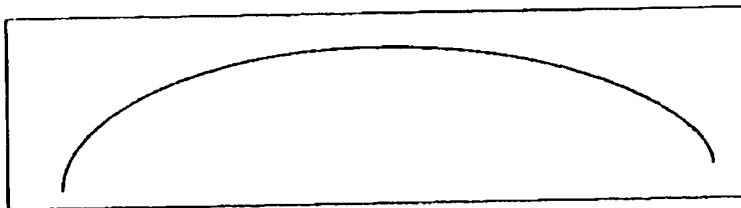
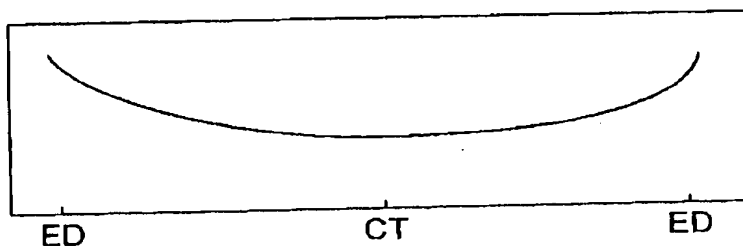


FIG.6C

ELECTRODE
MOVING SPEED



X(POSITION ON A WAFER)

2025-09-04 09:55:00

FIG.7A

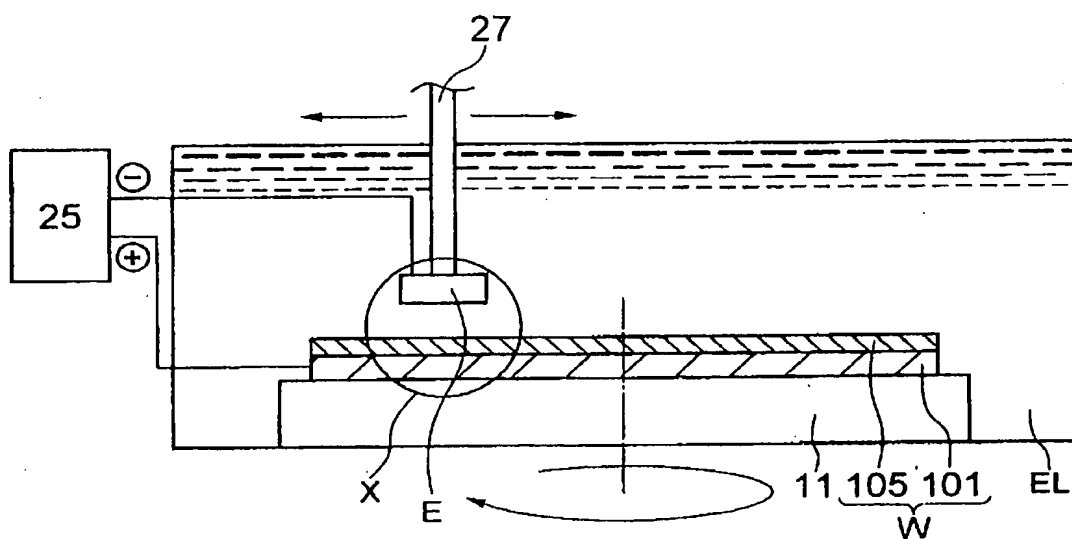
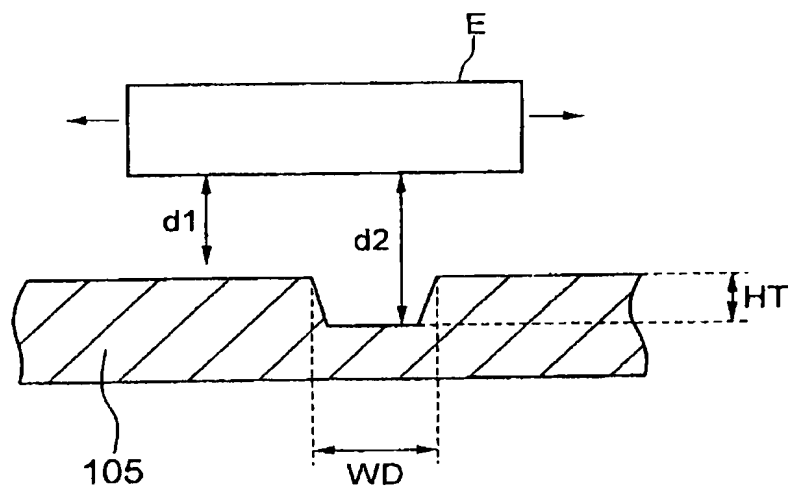


FIG.7B



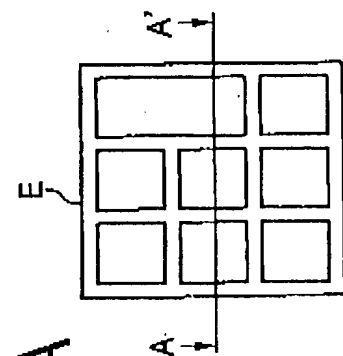


FIG. 8C

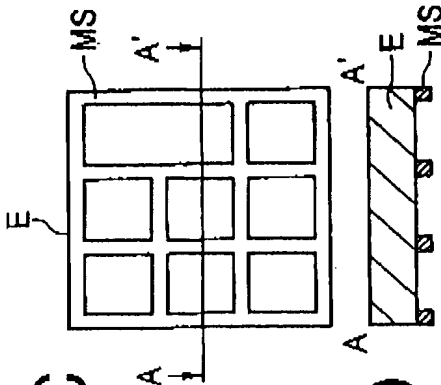
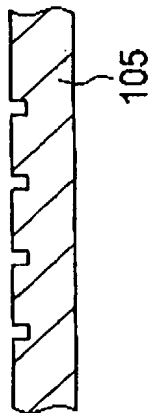
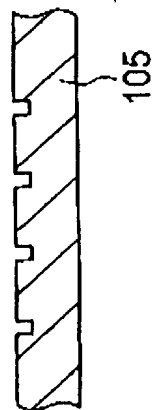
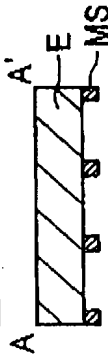


FIG. 8B



FIG. 8D



105

105

FIG.8E

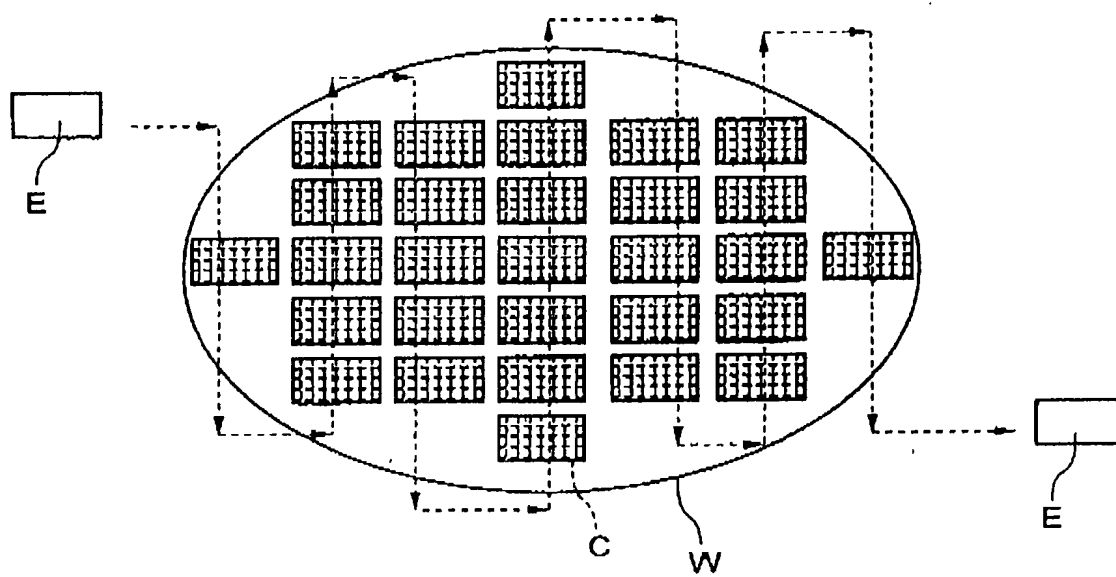


FIG.9A

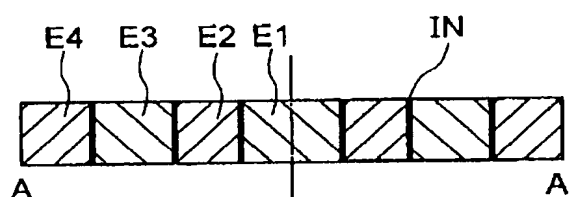


FIG.9B

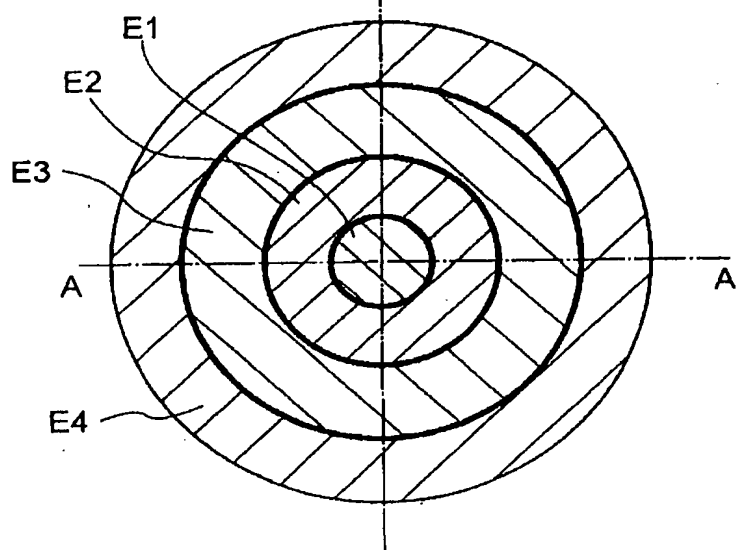


FIG.10A

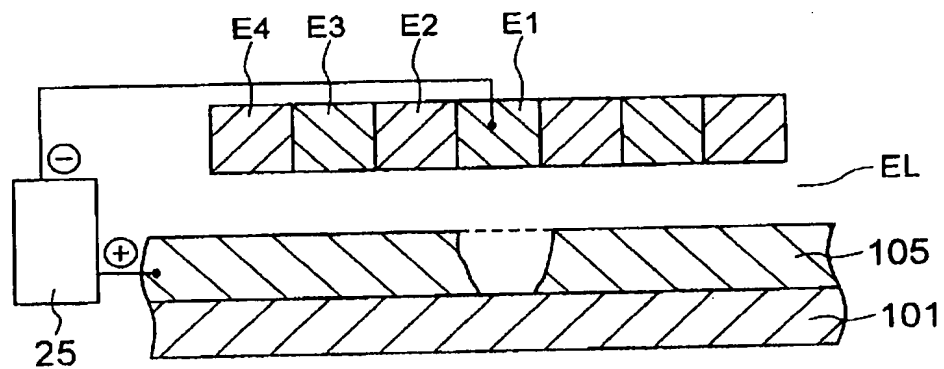


FIG.10B

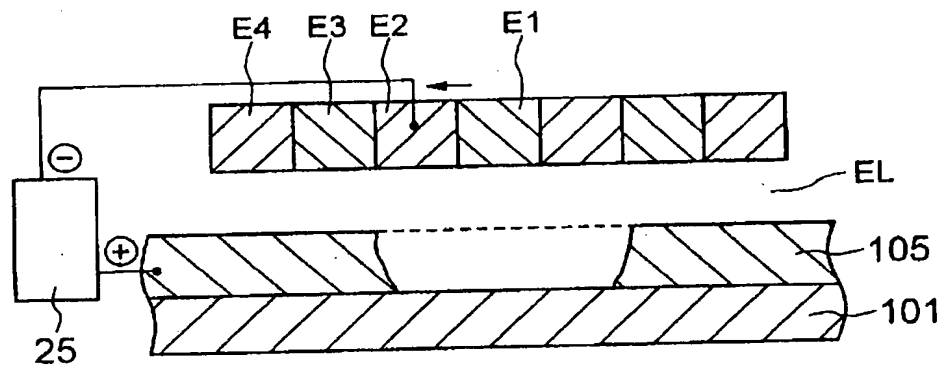


FIG.10C

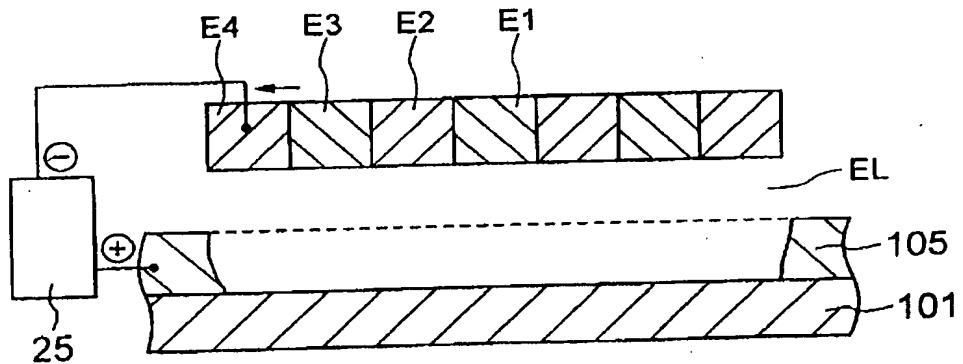


FIG.11A

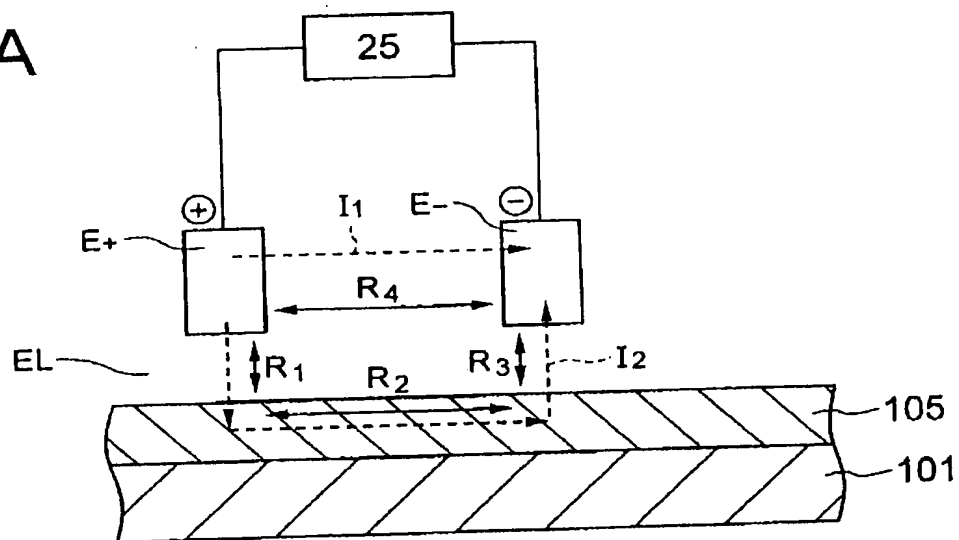


FIG.11B

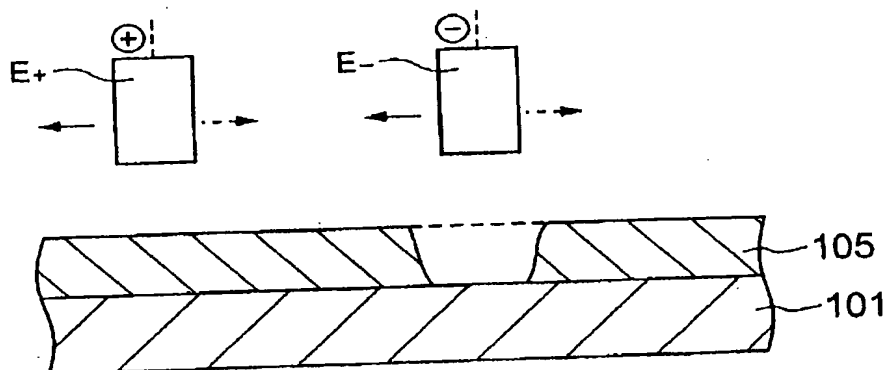


FIG.12A

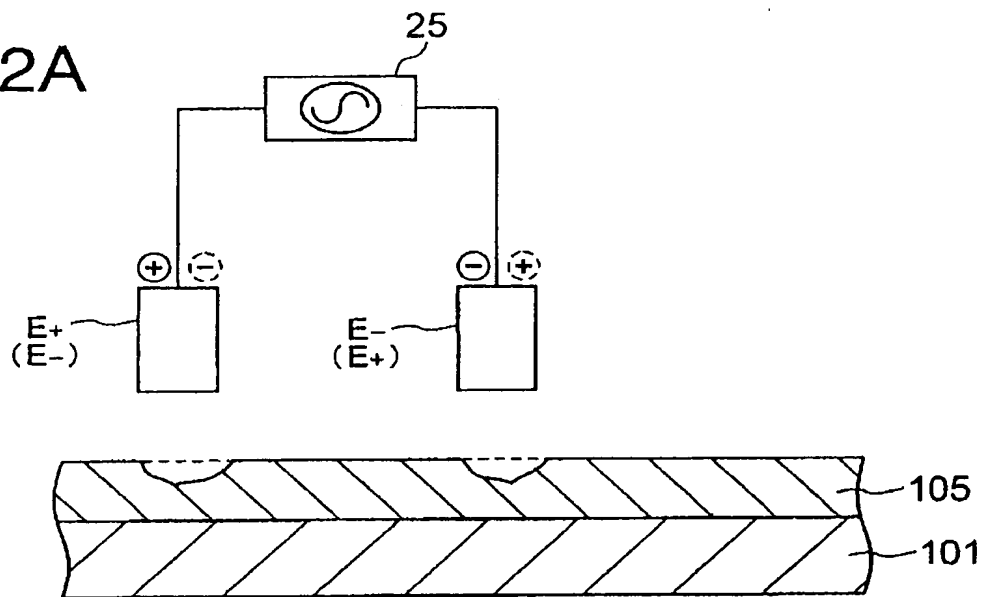


FIG.12B

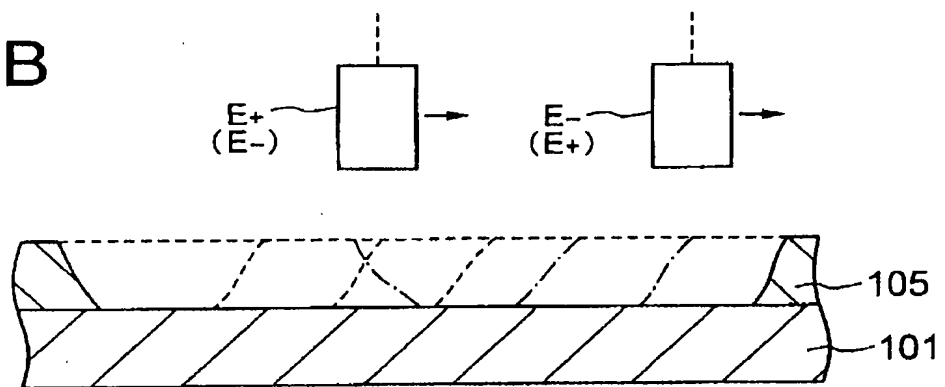


FIG.13A

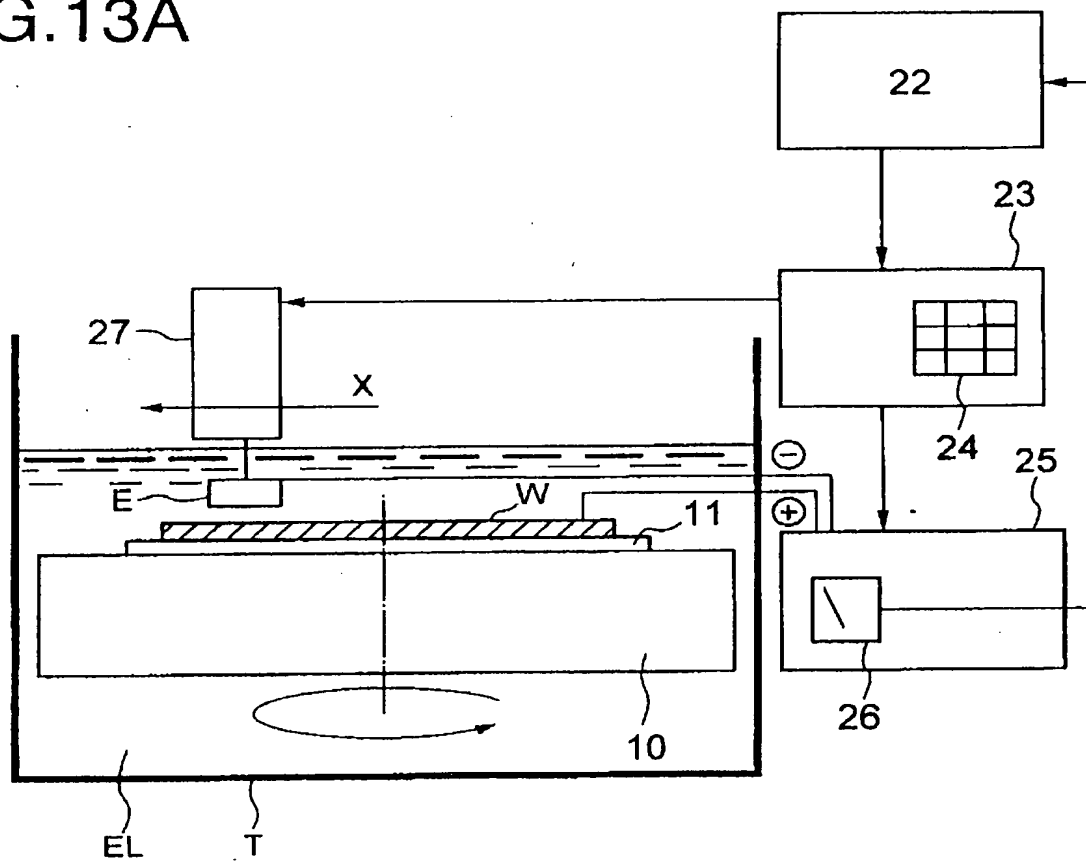


FIG.13B

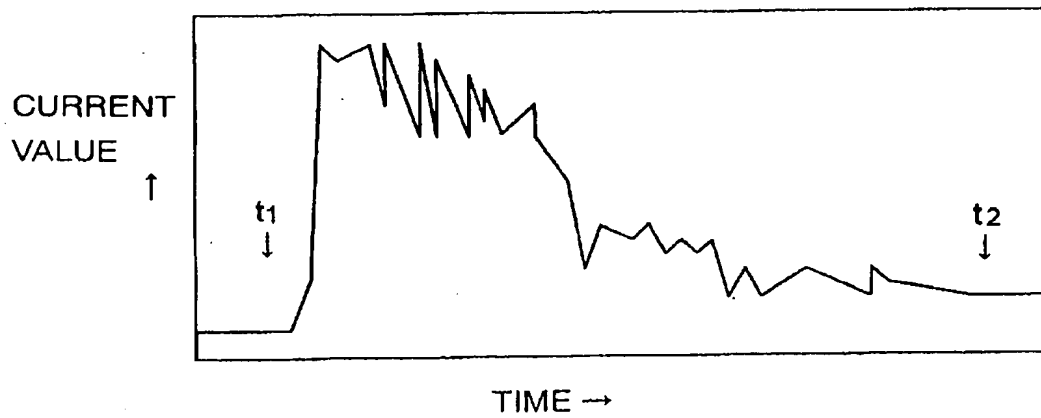


FIG.15

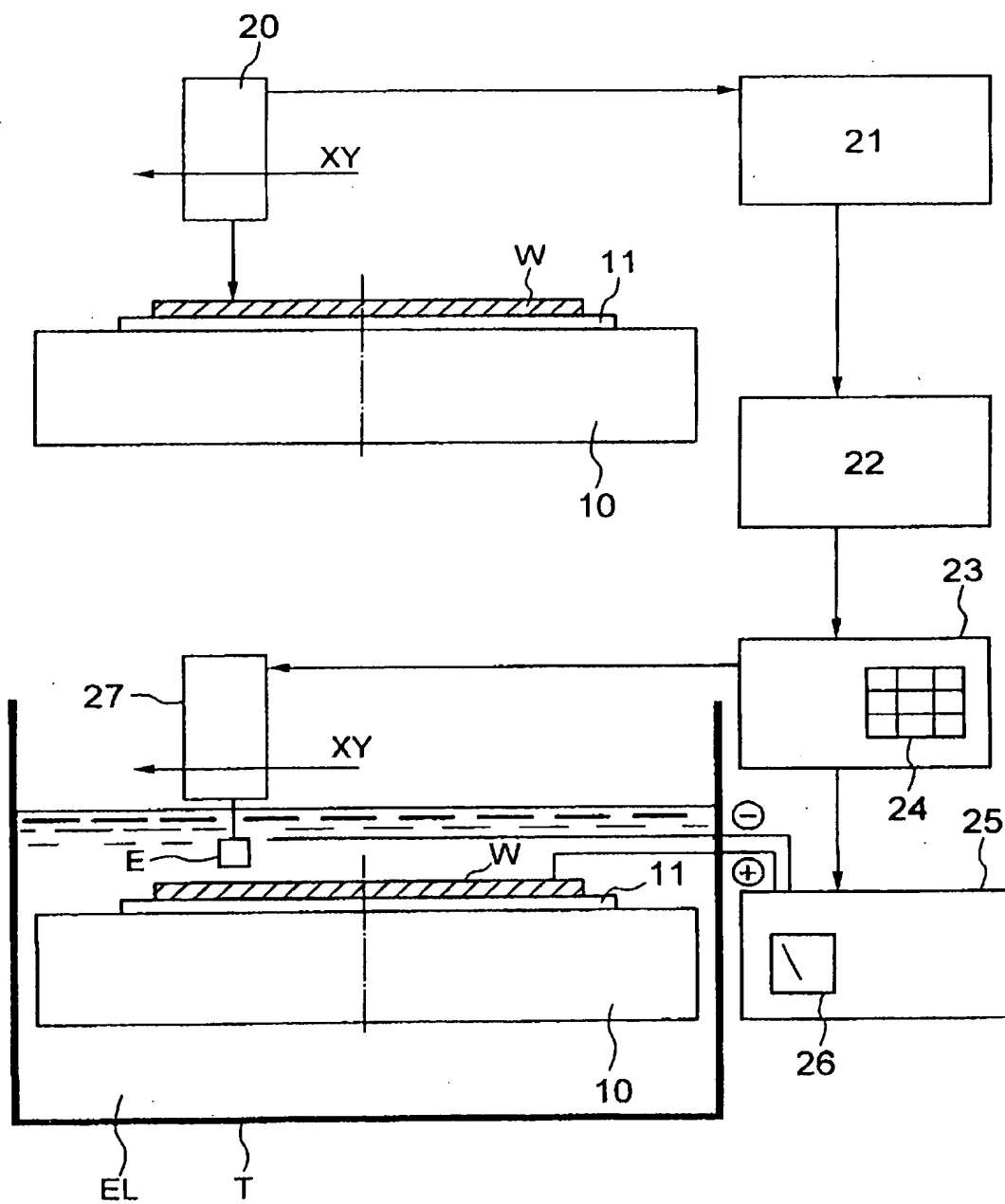


FIG.16A

FILM
THICKNESS
↑

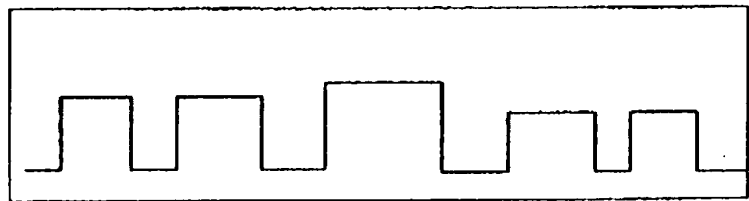


FIG.16B

AMOUNT OF
REMOVAL
↑

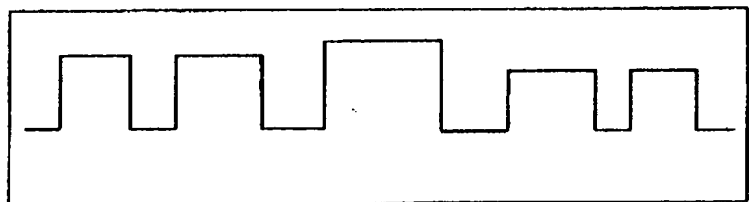


FIG.16C

ELECTRODE
MOVING SPEED
↑

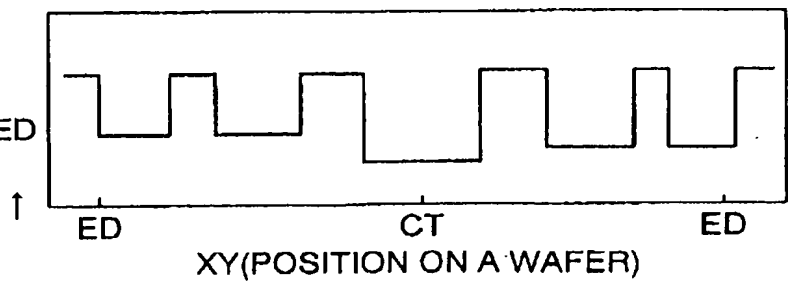
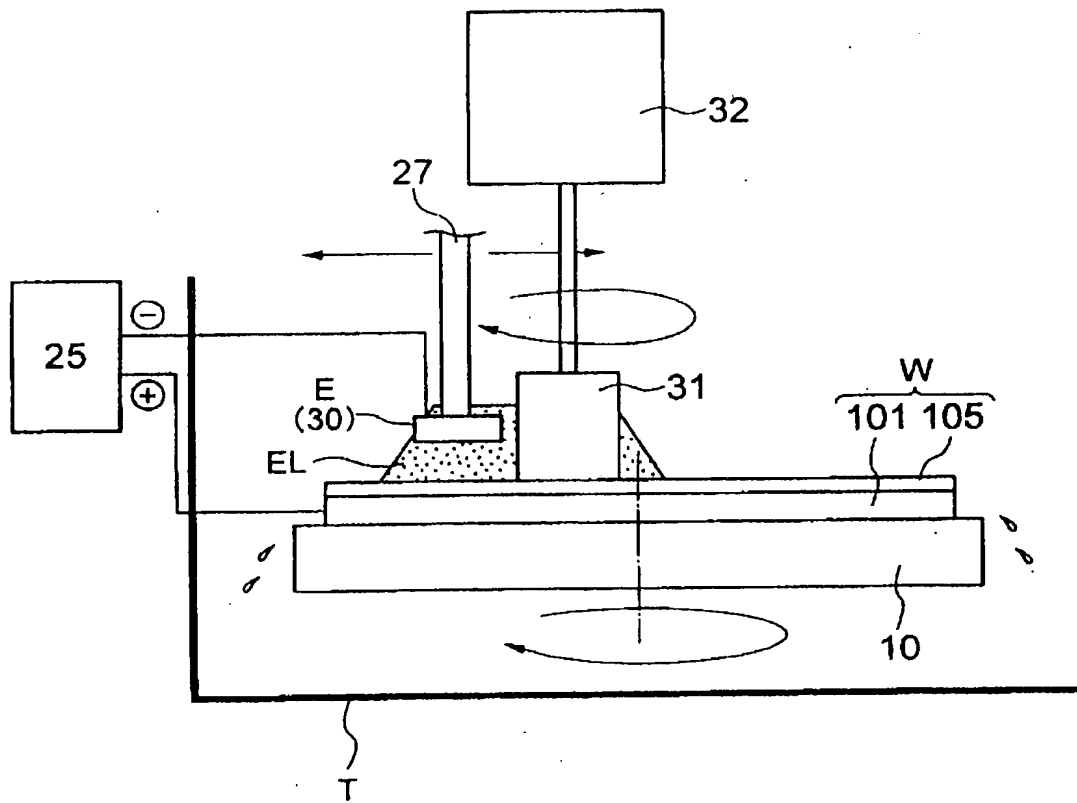


FIG. 17



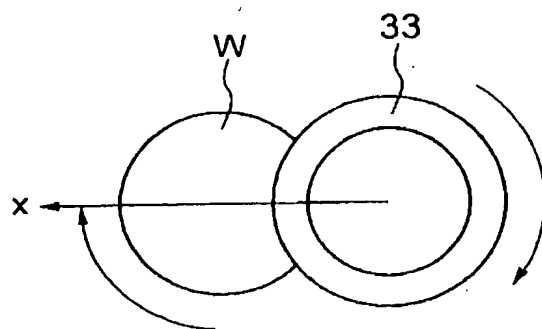
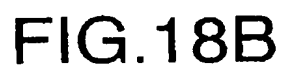
[illegible]

FIG.19A

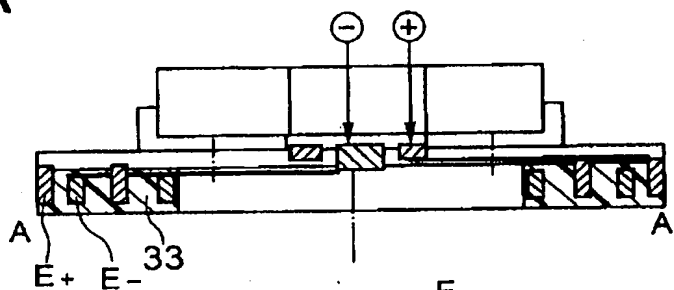


FIG.19B

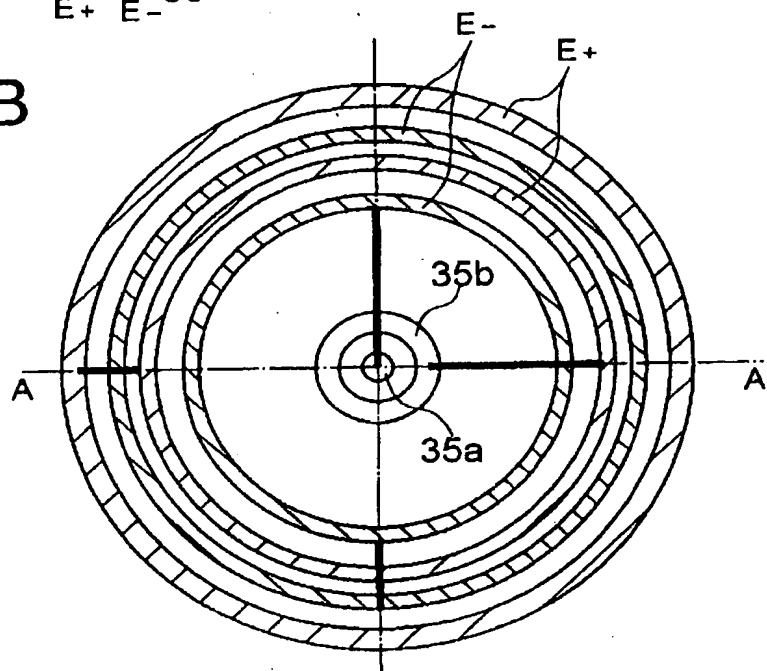


FIG.19C

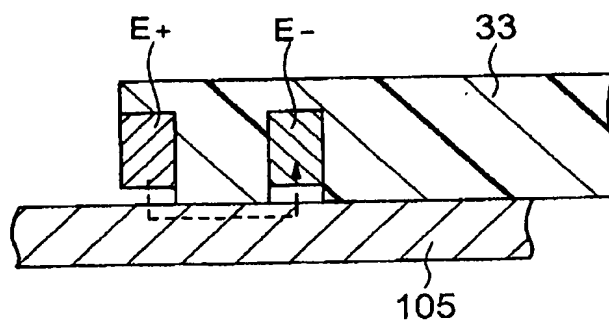


FIG.20A

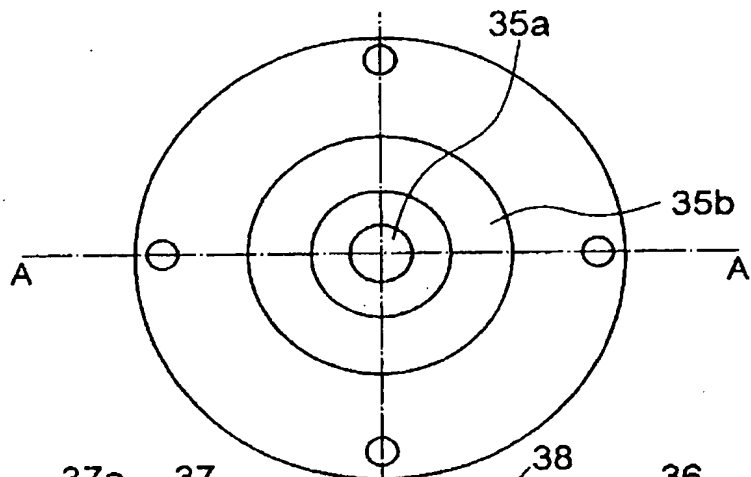


FIG.20B

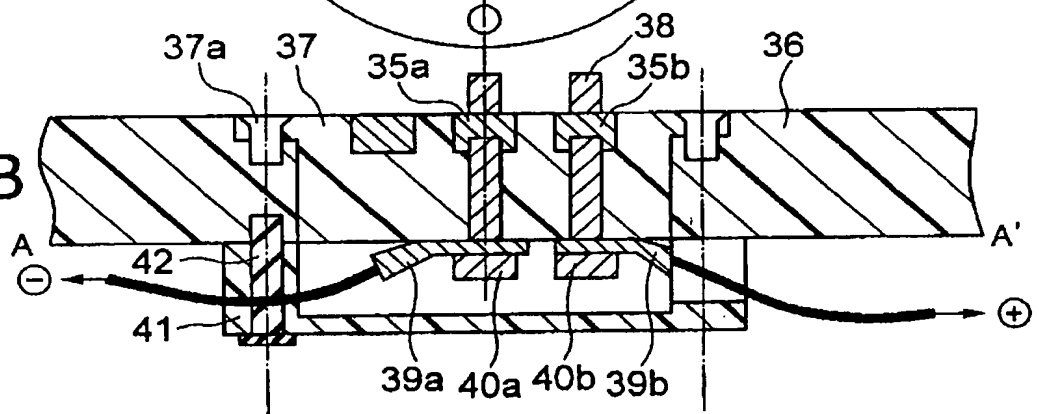


FIG. 21A

FIG.21A

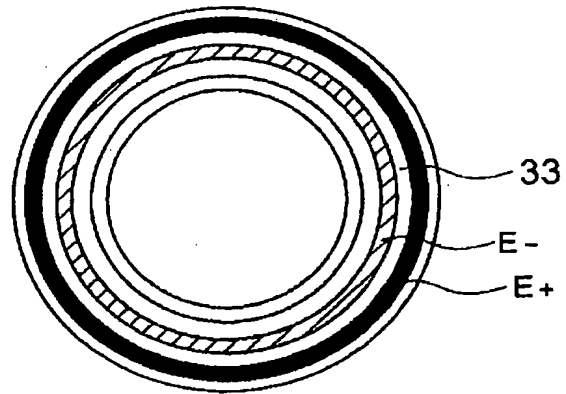


FIG.21B

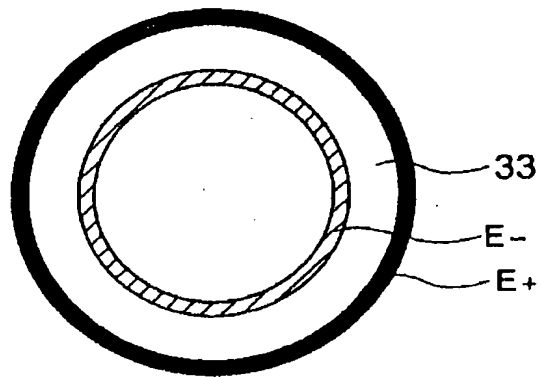


FIG.21C

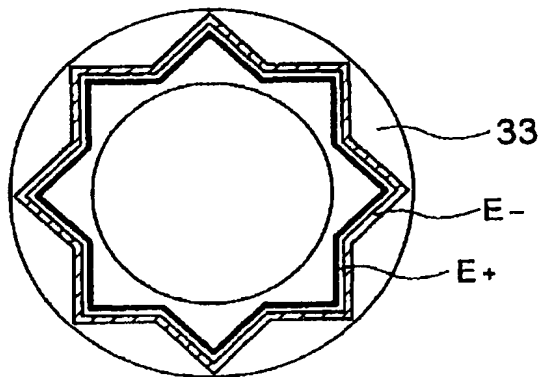


FIG.22A

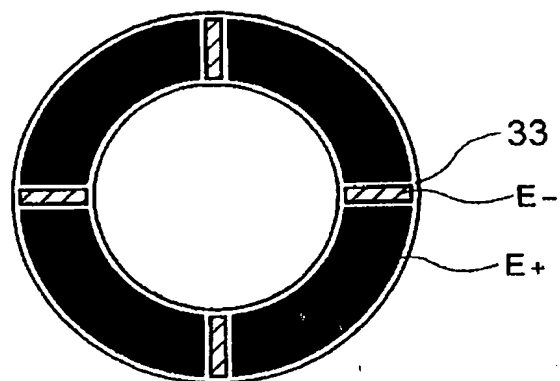


FIG.22B

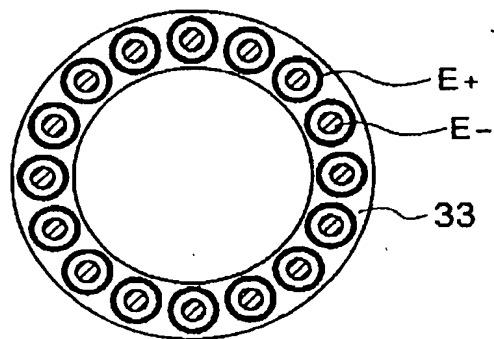


FIG.22C

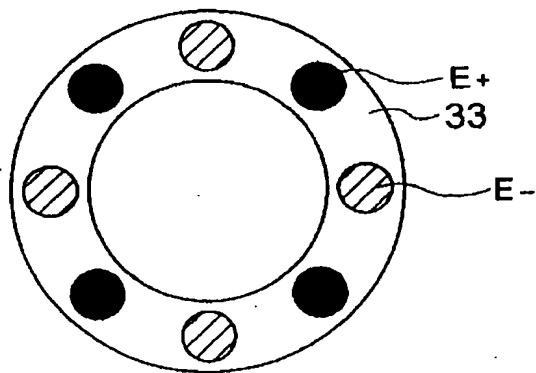


FIG.23A

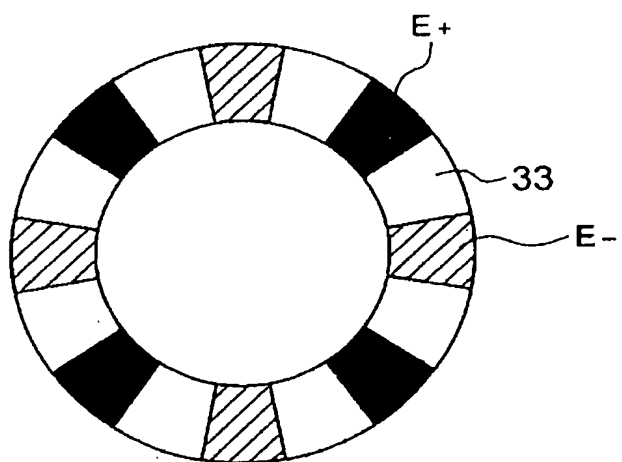


FIG.23B

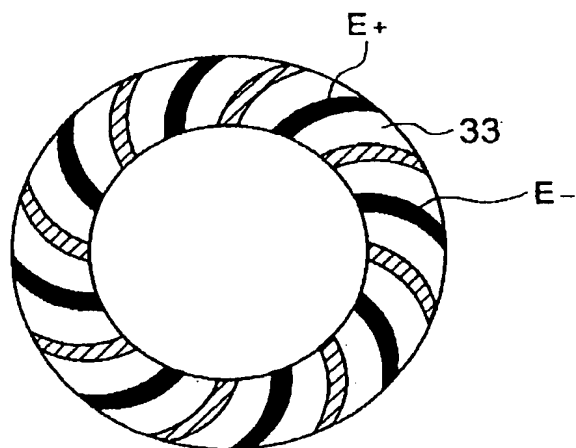


FIG.24A

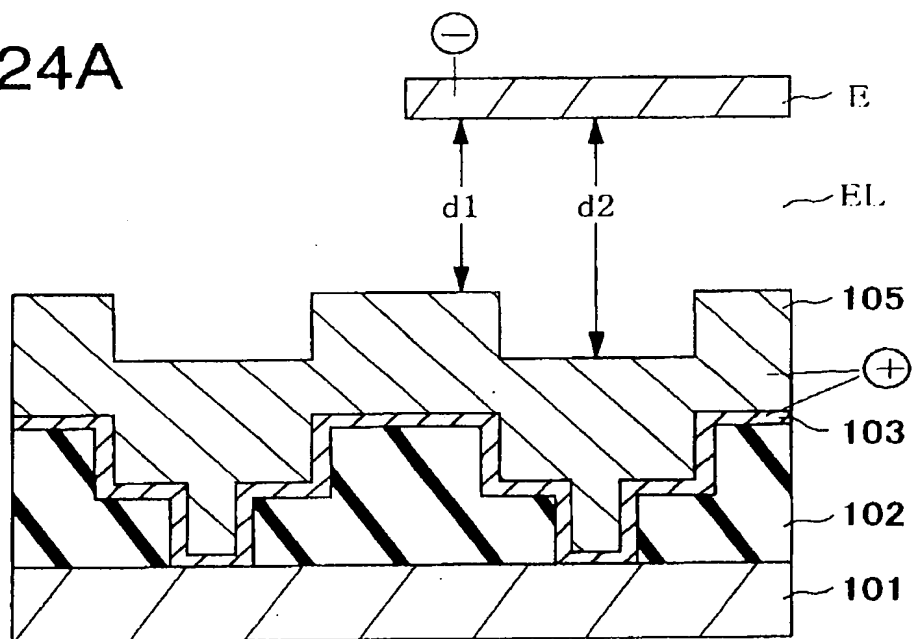


FIG.24B

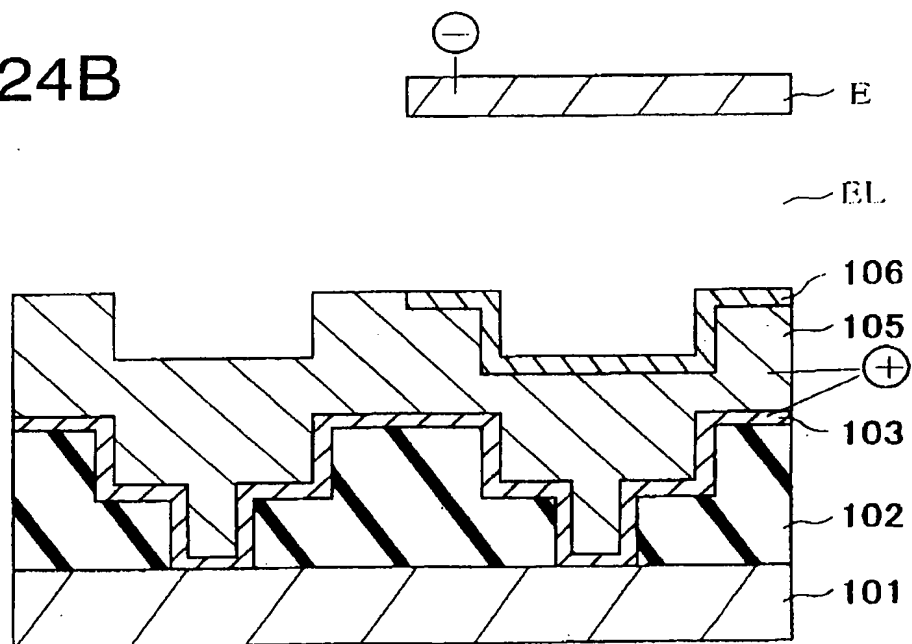


FIG.25A

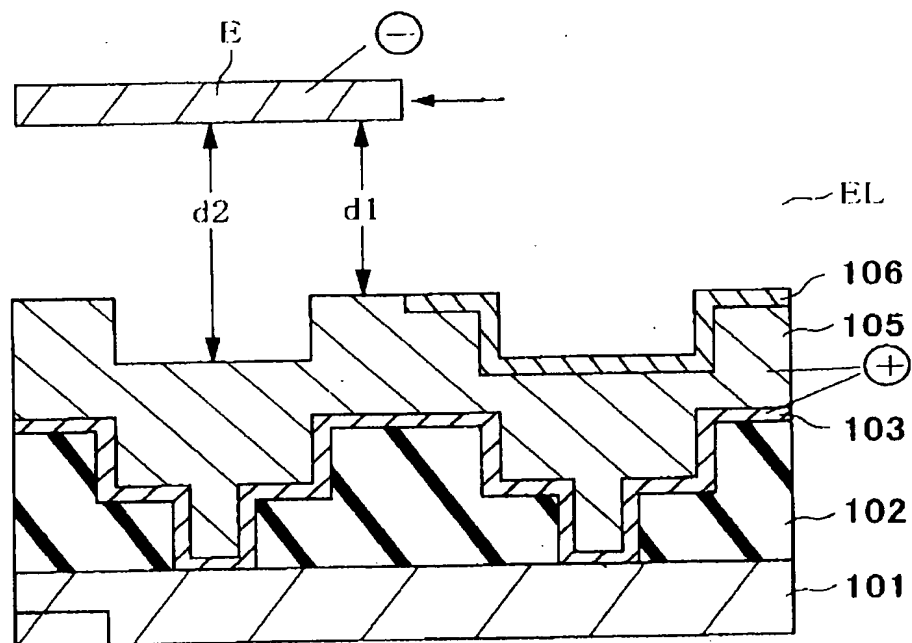


FIG.25B

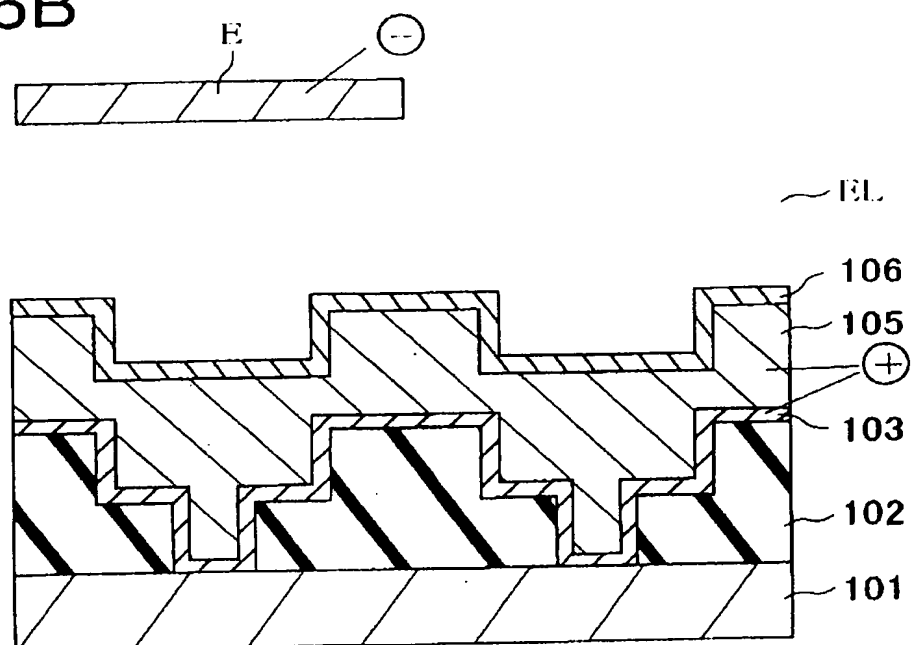


FIG.26A

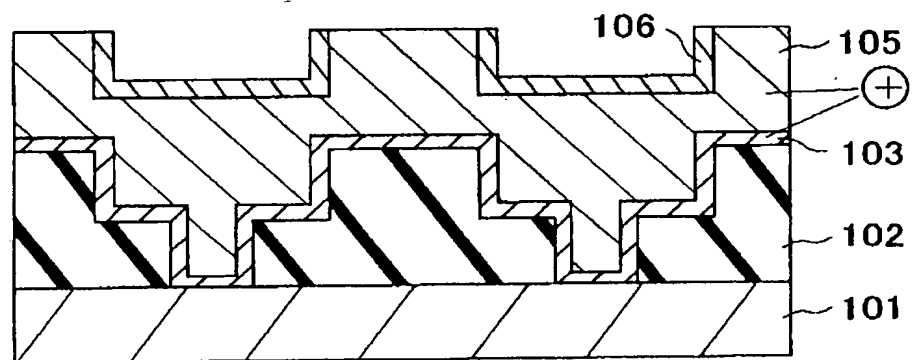


FIG.26B

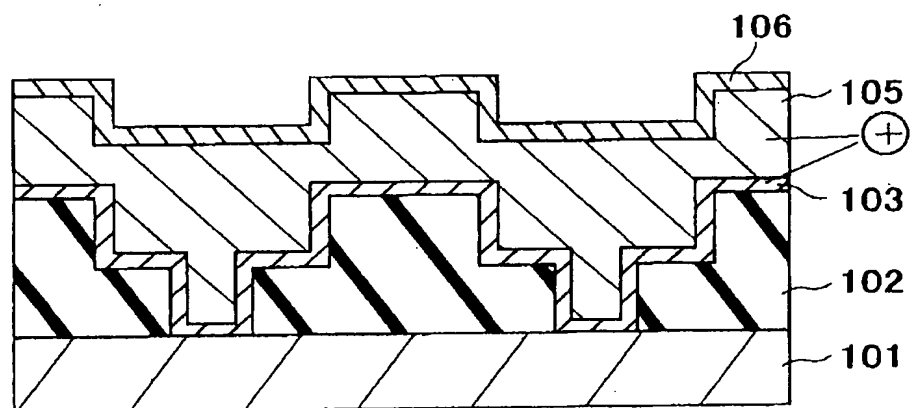
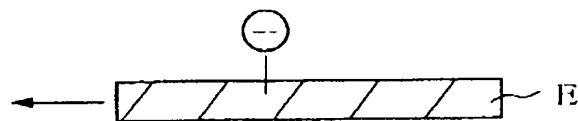


FIG.27A

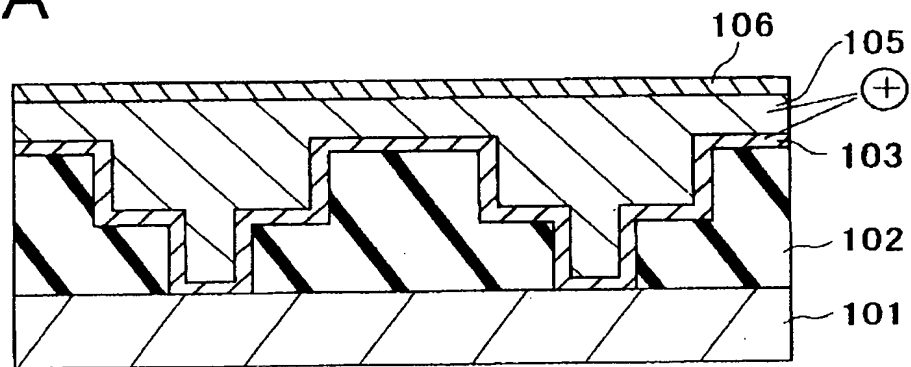


FIG.27B

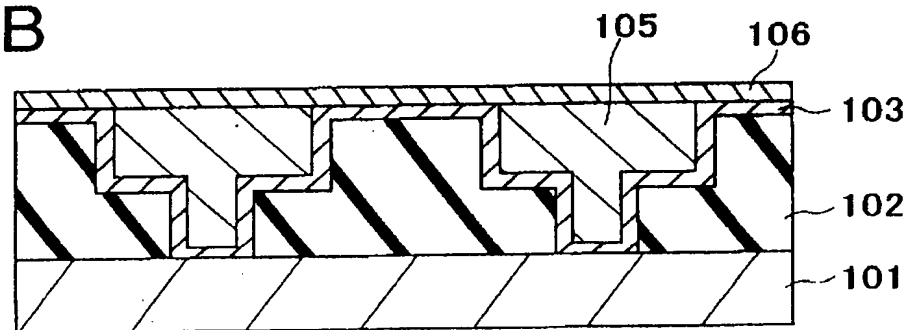


FIG.27C

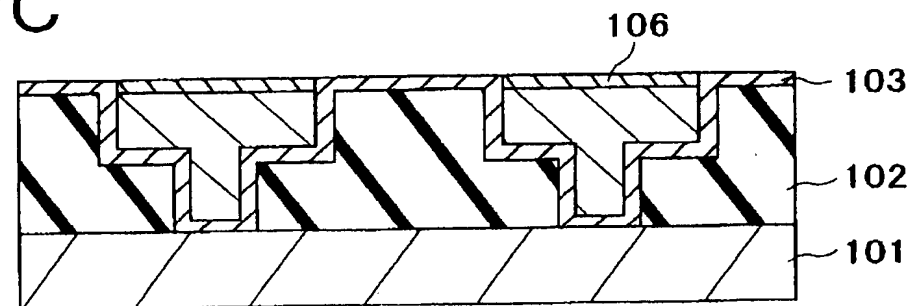


FIG. 28

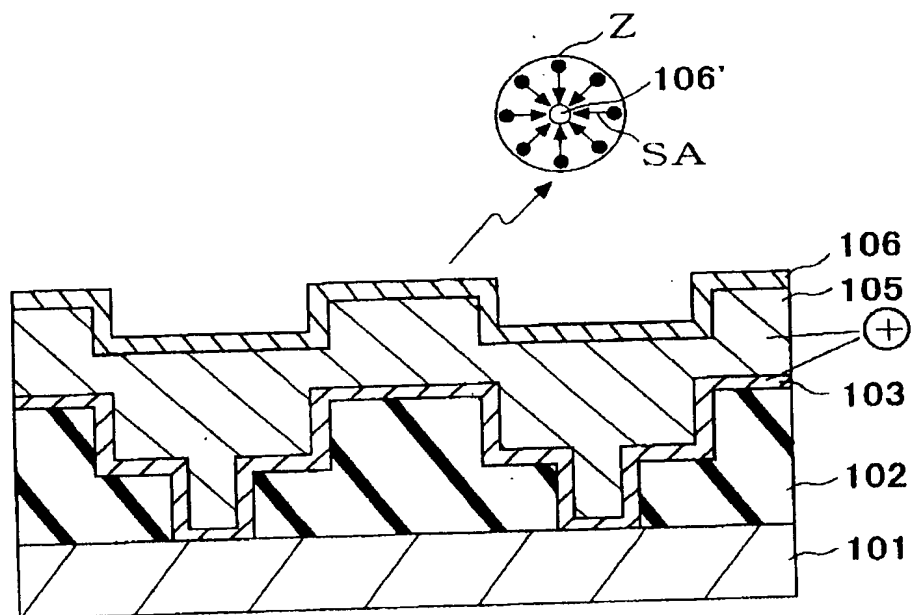


FIG. 29

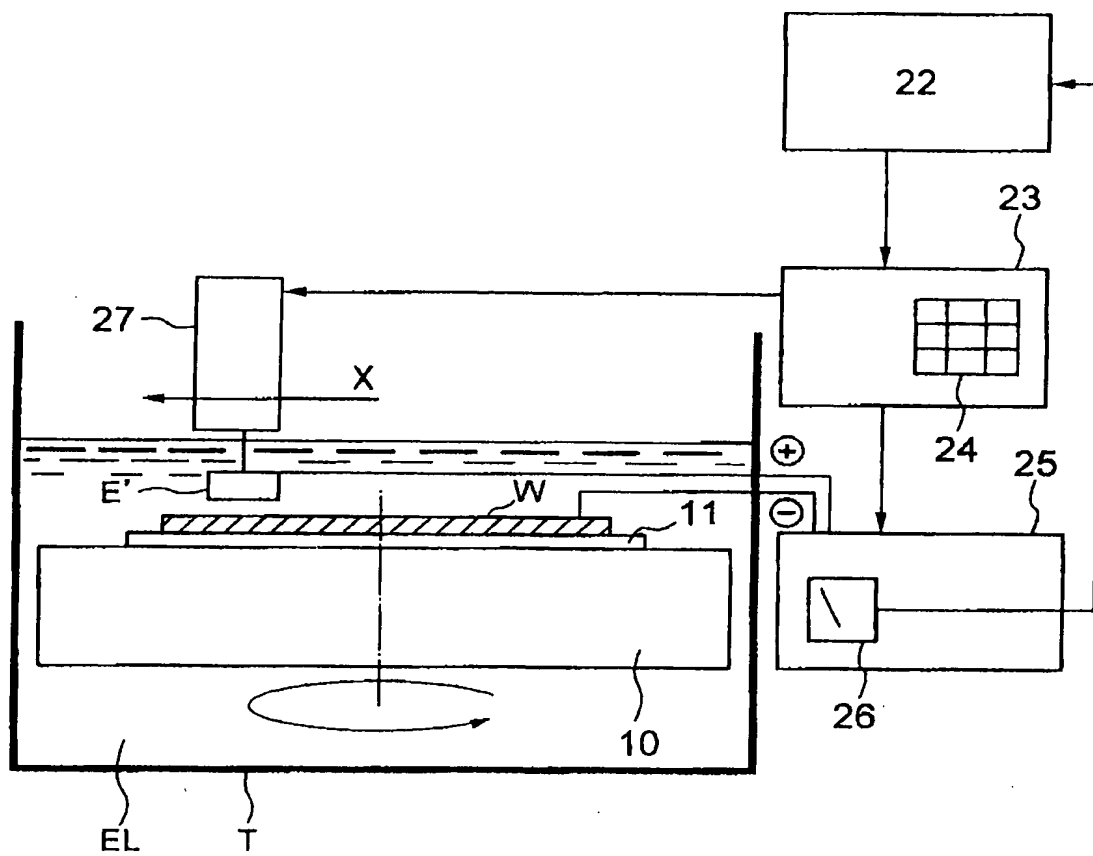


FIG.30A

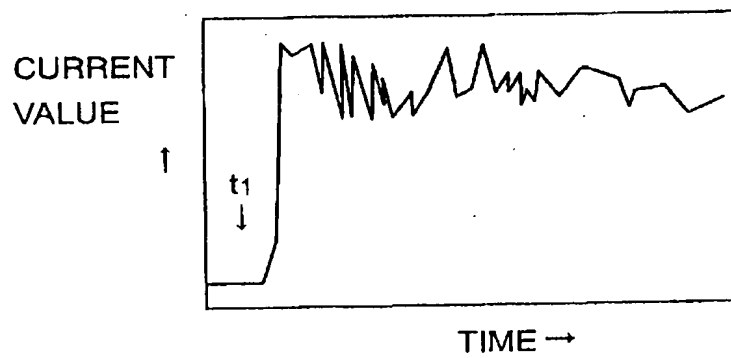


FIG.30B

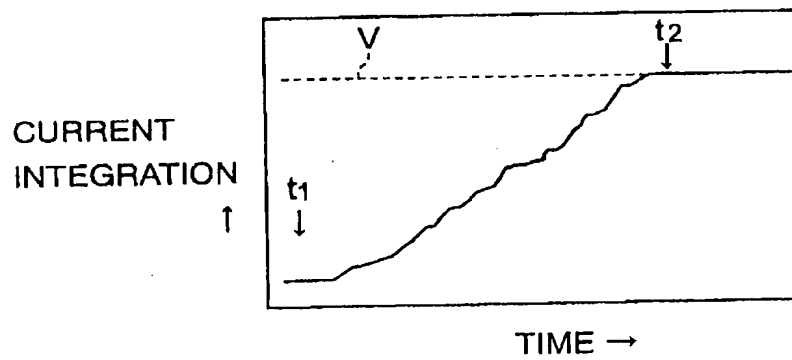


FIG. 31

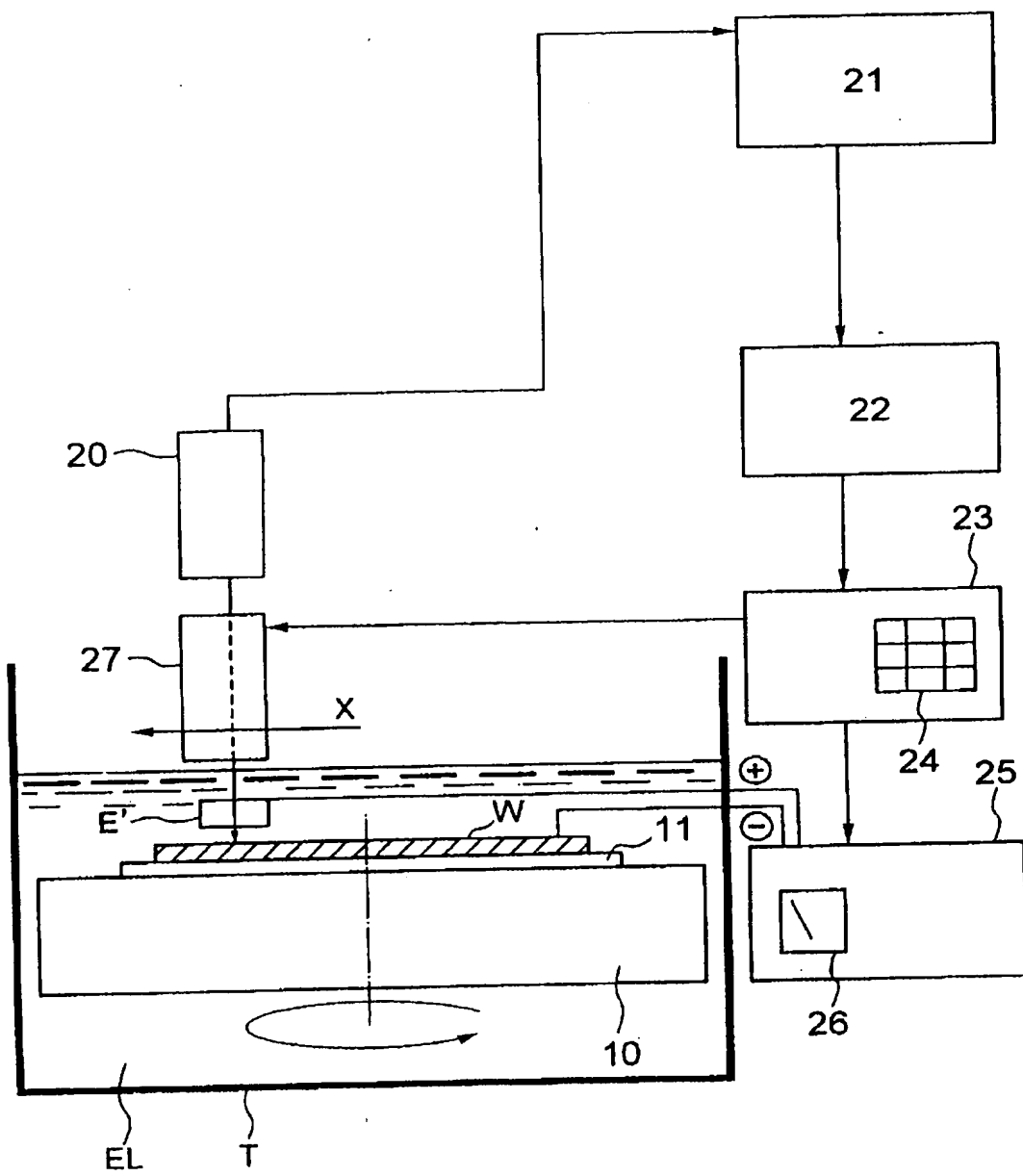


FIG. 32

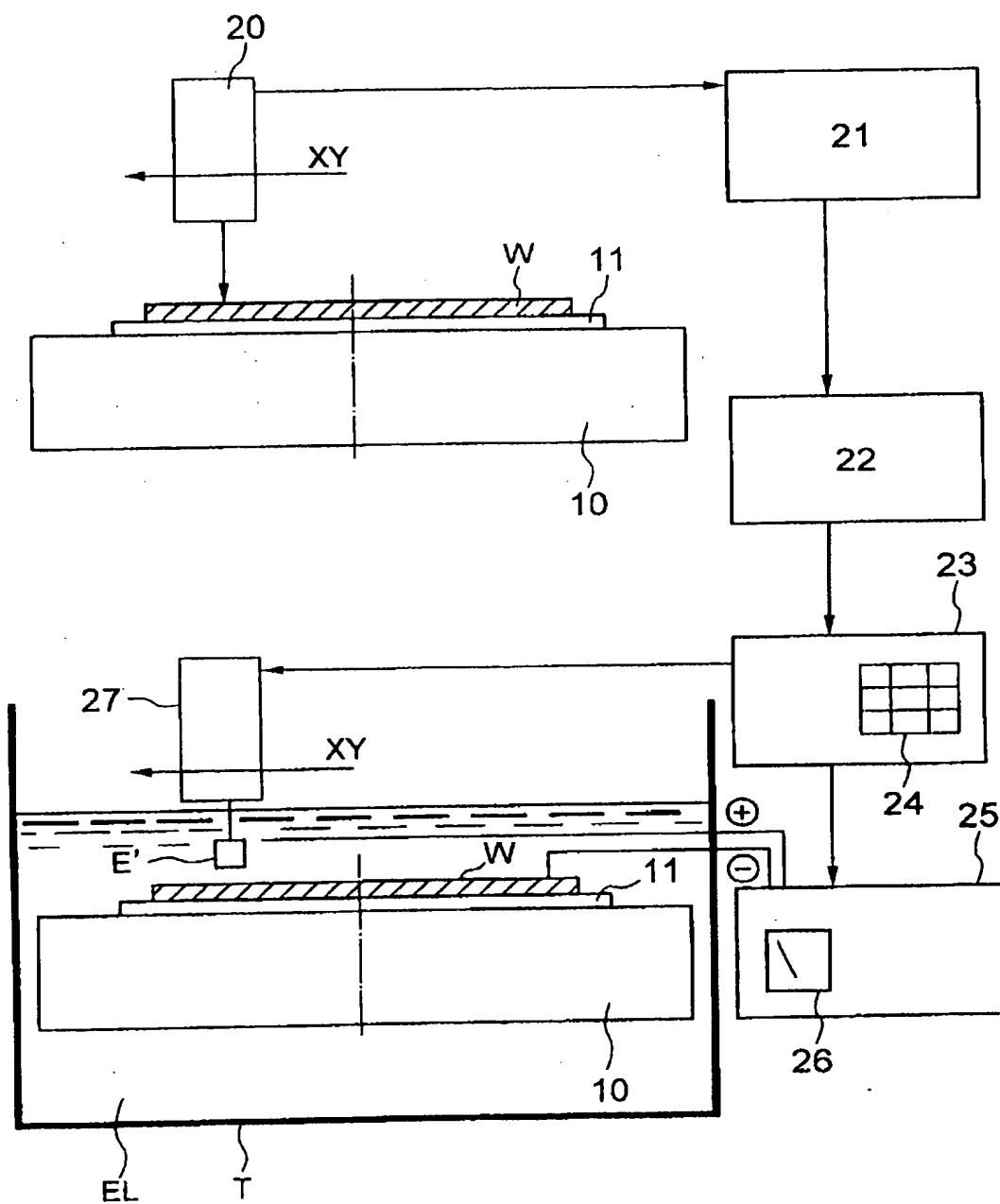


FIG.33A

SURFACE
THICKNESS
↑

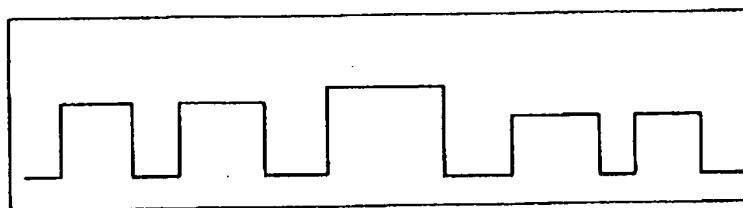


FIG.33B

AMOUNT OF
DEPOSITION
↑

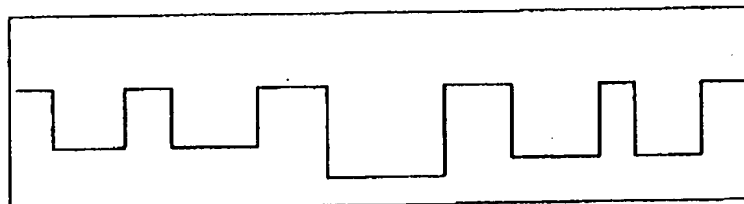
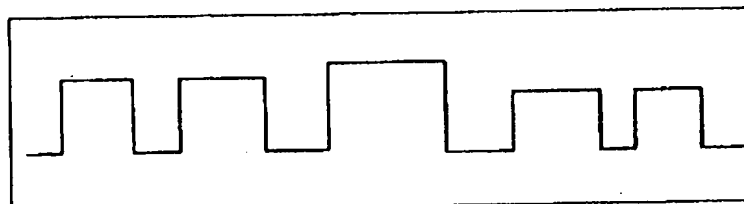


FIG.33C

ELECTRODE
MOVING SPEED
↑



X(POSITION ON A WAFER)

FIG.34A

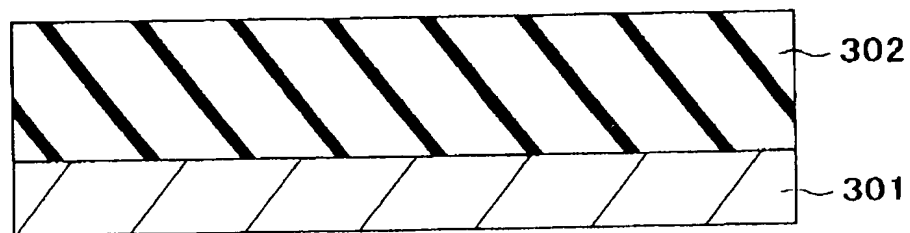


FIG.34B

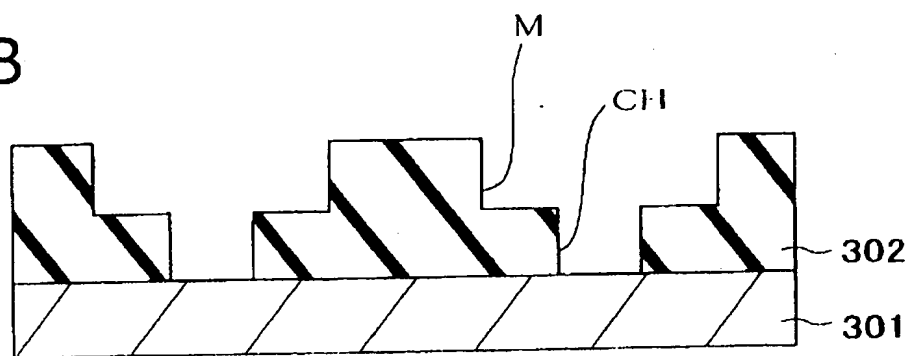


FIG.34C

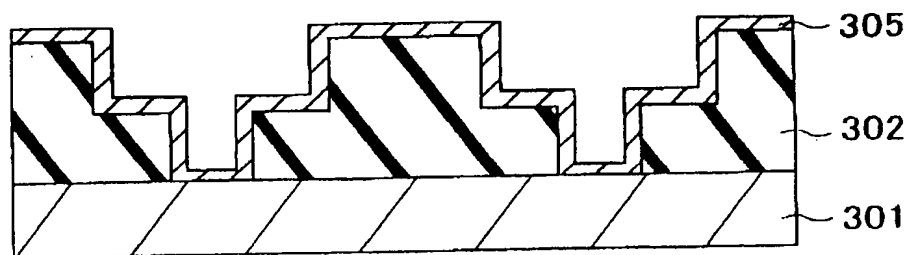


FIG.35A

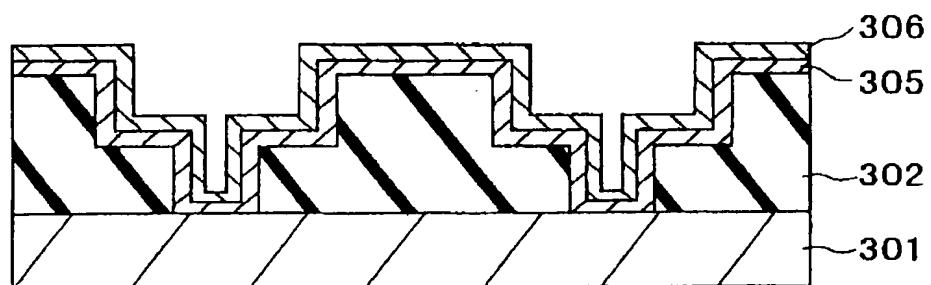


FIG.35B

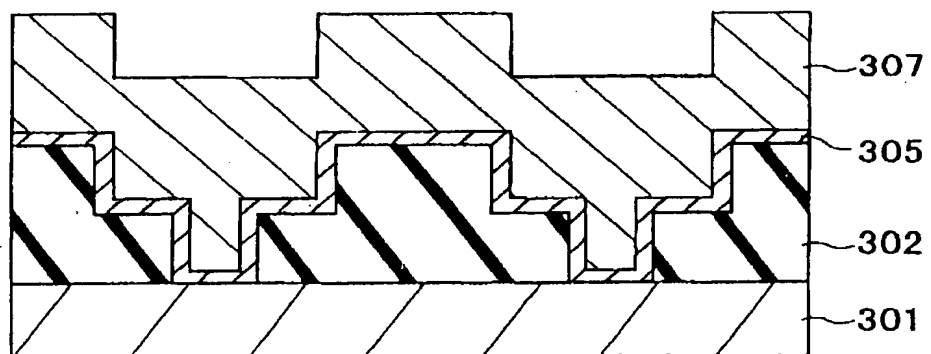


FIG.35C

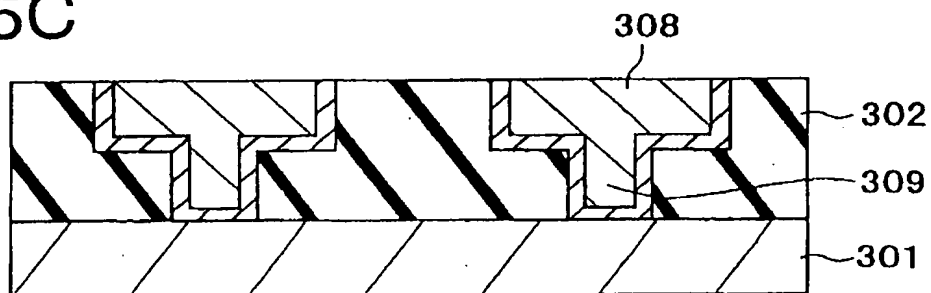


FIG. 36

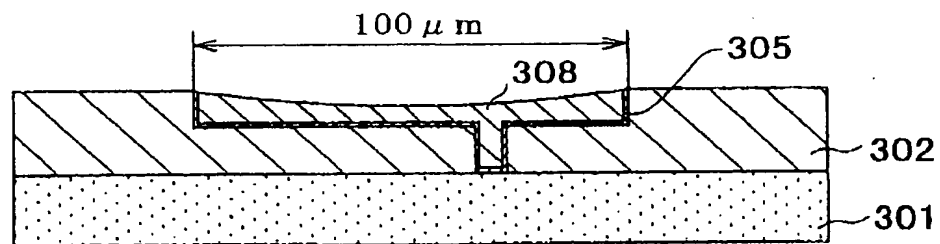


FIG. 37

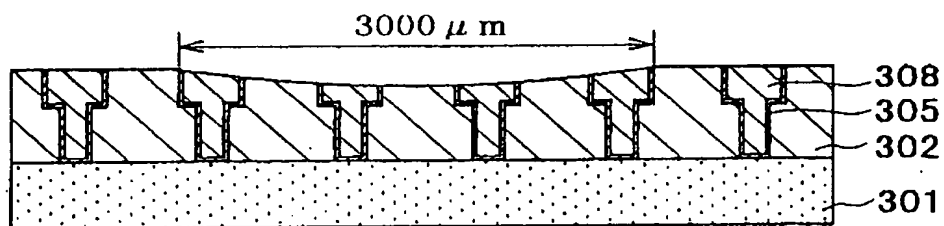


FIG. 38

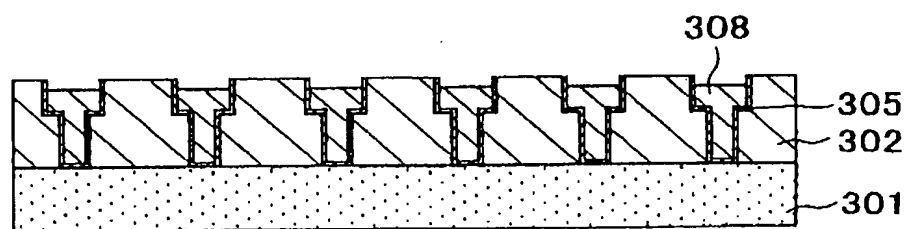


FIG. 39

